

Data sheet acquired from Harris Semiconductor

CD4045B Types

CMOS 21-Stage Counter

High-Voltage Types (20-Volt Rating)

string of 21 counter stages, two outputshaping flip-flops, two inverter output drivers, and input inverters for use in a crystal oscillator. The CD4045B configuration provides 21 flip-flop counting stages, and two flipflops for shaping the output waveform for a 3.125% duty cycle. Push-pull operation is provided by the inverter output drivers.

The first inverter is intended for use as a crystal oscillator/amplifier. However, it may be used as a normal logic inverter if desired. A crystal oscillator circuit can be made less sensitive to voltage-supply variations by the use of source resistors. In this device, the sources of the p and n transistors have been brought out to package terminals. If external resistors are not required, the sources must be shorted to their respective substrates (Sp to VDD, Sn to VSS). See Fig. 1. The first inverter in conjunction with an outboard inverter, such as 1/6 CD4069, and Rx, Cx, and RS can also be used to construct an RC oscillator. The following data is supplied as a guide in the selection of values for RX, R_S, and C_X used in Fig. 11:

- 1. R_X max = 10 $M\Omega$ with R_S = 10 $M\Omega$ and C_X = 50 pF
- 2. C $_{\rm X}$ max = 25 $\mu{\rm F}$ with R_S = 560 k Ω and R $_{\rm X}$ = 50 k Ω

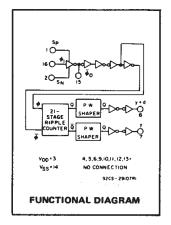
The CD4045B types are supplied in 16-lead dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic packages (Esuffix), and in chip form (H suffix).

Applications:

- Digital equipment in which ultra-low dissipation and/or operation using a battery source is required.
- Accurate timing from a crystal oscillator for timing applications such as wall clocks, table clocks, automobile clocks, and digital timing references in any circuit requiring accurately timed outputs at various intervals in the counting sequence.
- Driving miniature synchronous motors, stepping motors, or external bipolar transistors in push-pull fashion.

Features:

- Very low operating dissipation <1 mW (typ.) Θ VDD = 5 V, $f\phi$ = 1 MHz
- Medium speed (typ.) . . . $f\phi = 25 \text{ MHz @ V}_{DD} = 10 \text{ V}$
- 100% tested for quiescent current at 20 V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, Standard Specifications for Descripiton of 'B' Series CMOS Devices"



MAXIMUM RATINGS, Absolute-Maximum Values: DC SUPPLY-VOLTAGE RANGE, (V_{DD}) Voltages referenced to V_{SS} Terminal) -0.5V to +20V INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to V_{DD} +0.5V DC INPUT CURRENT, ANY ONE INPUT ±10mA POWER DISSIPATION PER PACKAGE (PD): For $T_A = -55^{\circ}$ C to +100°C For $T_A = +100^{\circ}$ C to +125°C. Derate Linearity at 12mW/°C to 200mW DEVICE DISSIPATION PER OUTPUT TRANSISTOR FOR $T_A = FULL$ PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW OPERATING-TEMPERATURE RANGE (T_{SC}) 55°C to +125°C STORAGE TEMPERATURE RANGE (T_{SC}) -65°C to +150°C LEAD TEMPERATURE (DURING SOLDERING): At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max +265°C

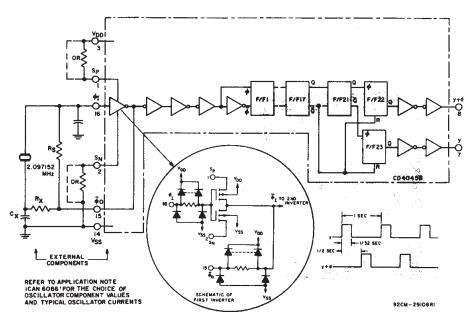


Fig. 1 - CD4045B and outboard components in a typical 21-stage counter application.

CD4045B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							ם א
	٧o	VIN	۷ _{DD}						+25		Т
	(v)	(V)	(V)	-55	-40	+85	+125	Min.	Тур.	Max.	s
Quiescent Device	_	0,5	5	5	5	150	150		0.04	5	
Current, IDD Max.	— <u>†</u>	0,10	10	. 10	10.	300	300	_	0.04	10	μA
* .		0,15	15	20	20	600	600	_	0.04	20	μ^
	_	0,20	20	100	100	3000	3000		0.08	100	<u>l</u>
Output Low (Sink)	0.4	0,5	5	4.5	4.3	2.9	2.5	3.6	7	_	
Current IOL Min.	0.5	0,10	10	11.2	10.5	7.7	6.3	9.1	18	_	
	1.5	0,15	15	29.4	28	19.6	16.8	23.8	47	_	mA
Output High (Source)	4.6	0,5	5	-4.5	-4.3	-2.9	-2.5	-3.6	-7	_]'''' <u>`</u>
Current, IOH Min.	9.5	0,10	10	-11.2	-10.5	-7.7	-6.3	-9.1	-18	_]
<u> </u>	13.5	0,15	15	-29.4	-28	-19.6	-16.8	-23.8	-47	_]
Pin 15 Output	0.4,4.6	0,5	5				±0.1	±0.18	_	mA	
Low and High	0.5,9.5	0,10	10				±0.2	±0.3	_		
Current, IOL, IOH	1.5,13.5	0,15	15	_			±0.5	±1	_	l	
Output Voltage:	-	0,5	5	0.05					—	0.05	V
Low-Level,	_	0,10	10	0.05 0.05			_	_	0.05		
VOL Max.		0,15	15				_	_	0.05		
Output Voltage:		0,5	5	4.95			4.95	- 5	_	"	
High-Level,	_	0,10	10	9.95			9.95	10	_		
VOH Min.	_	0,15	15	14.95			14.95	15	_	1	
Input Low	0.5,4.5		5	1.5			-	-	1.5		
Voltage	1,9	_	10	3				_	-	3	
۷۱۲ Max.	1.5,13.5	_	15	4			_	- T	4	V	
Input High	0.5,4.5	_	5	3.5 7			3.5	_	_	ľ	
Voltage,	1,9		10				7	_	_		
VIH Min.	1.5,13.5	-	15	11				11	-	_	
Input Current I _{IN} Max.	-	0,18	18	±0.1	±0.1	±1	±1	-	±10-5	±0.1	μΑ

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges

CHARACTERISTIC	V _{DD}	LIMITS		
	(v)	Min.	Max.	UNITS
Supply-Voltage Range (For T _A = Full Package- Temperature Range)	_	3	18	٧
Minimum Input-Pulse Width, tw	5 10 15	- - -	100 50 40	ns
Maximum Input-Pulse Frequency, fφ (External Pulse Source)	5 10 15	5 12 15		MHz

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DYNAMIC ELECTRICAL CHARACTERISTICS at T_A = 25°C; input $t_r,\,t_f$ = 20 ns, C_L = 50 pF, R_L = 200 $k\Omega$

	TEST			LIMITS			
CHARACTERISTIC	CONDITIONS	V _{DD}	Min.	Тур.	Max.	UNITS	
Propagation Delay Time:		5	_	2.2	5.5		
ϕ_{\parallel} to y or y+d out		10	_	0.9	2.7	μs	
tPHL, tPLH	1	15	-	0.65	2		
Transition Time:		5	_	25	50		
		10	-	13	25		
^t THL ^{, t} TLH		15		10	20	ns	
Minimum Input-Pulse Width		5	_	50	100	113	
		10	-	25	50		
^t W	1	15	-	20	40		
Input-Pulse Rise or Fall Time:		5	_		500		
	· .	10	-	-	500	μs	
$t_r \phi$, $t_f \phi$		15		–	500		
Maximum Input-Pulse		5	5	10	_		
Frequency:		10	12	25		MHz	
(External Pulse Source) f _φ		15	15	30	-		
Input Capacitance, C _{IN}	Any Input			5	7.5	pF	
Variation of Output Frequency		5	-	0.05	_		
(Unit-to-Unit)	f = 5 MHz	10	_	0.03	_	%	
		15	_ `	0.1	`		
RC Oscillator Operation							
Maximum Oscillator Frequency	$R_X = 50 k\Omega$,	5	45	60	75		
(See Fig. 11)	$R_S = 560 k\Omega$,	10	45	60	75	kHz	
fosc	$C_X = 50 pF$	15	45	60	75		

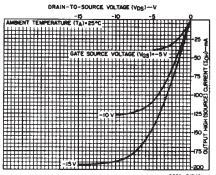


Fig. 4 — Typical output high (source) current characteristics.

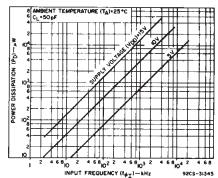


Fig. 7 — Typical power dissipation as a function of input frequency (21 counting stages).

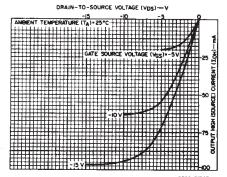


Fig. 5 – Minimum output high (source)

characteristics.

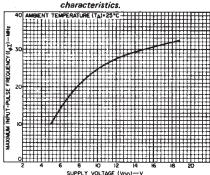


Fig. 8 — Typical maximum input-pulse frequency as a function of supply voltage.

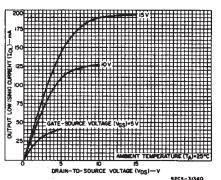


Fig. 2 — Typical output low (sink) current characteristics.

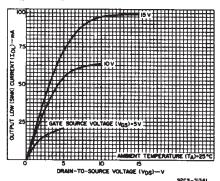
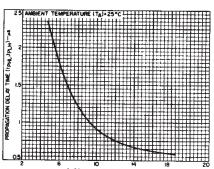


Fig. 3 – Minimum output low (sink) current characteristics.



2
6
V
18
2
Fig. 6 — Typical propagation delay time as a function of supply voltage (φ, to y or y + d out vs. V DD).

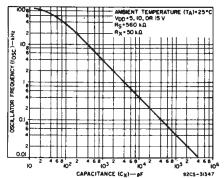


Fig. 9 — Typical RC oscillator frequency as a function of capacitance (C_X), See Fig. 11.

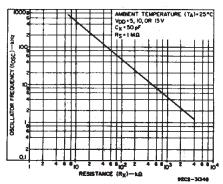


Fig. 10 — Typical RC oscillator frequency as a function of resistance (R_X),
See Fig. 11.

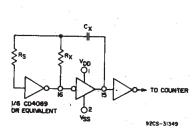


Fig. 11 - Typical RC circuit.

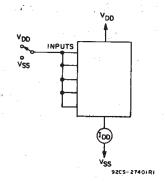


Fig. 12 - Quiescent-device-current test circuit.

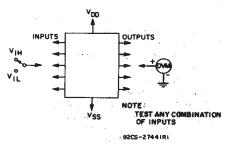


Fig. 13 - Noise-immunity test circuit.

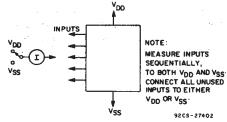


Fig. 14 - Input-leakage-current test circuit.

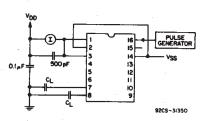
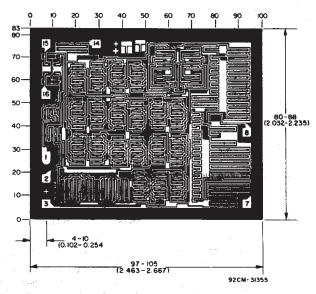


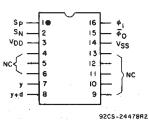
Fig. 15 - Dynamic power dissipation test circuit.



Chip dimensions and pad layout for CD4045B

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

TERMINAL DIAGRAM Top View



NC - NO CONNECTION

NOTE Observe power-supply terminal connections, V_{DD} is terminal No. 3 and V_{SS} is terminal No. 14 (not 16 and 8 respectively, as in other CD40008 Series 16-lead devices).

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